

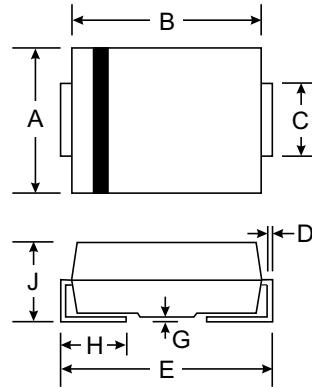
VOLTAGE RANGE: 400V
CURRENT: 1.0 A

Features

- Miniature Size, Surface Mount Device
- High Surge Capability
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- Packaged in 12mm Tape and Reel

Mechanical Data

- Case: SMA/DO-214AC, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.064 grams (approx.)



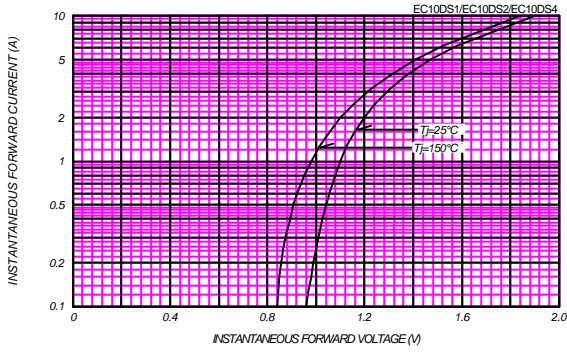
SMA(DO-214AC)		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.10	0.20
H	0.76	1.52
J	2.01	2.62
All Dimensions in mm		

Maximum Ratings @ T_A = 25°C unless otherwise specified

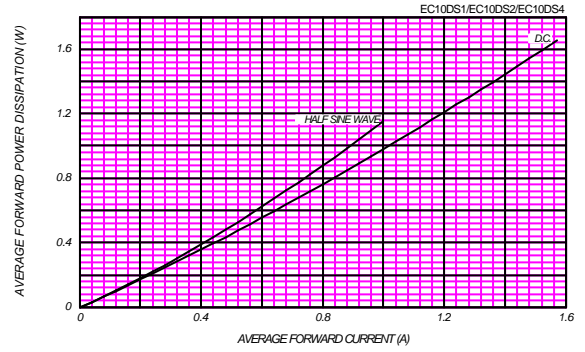
Characteristic	Symbol	EC10DS4	Unit
Repetitive Peak Reverse Voltage	VRRM	400	V
Non-repetitive Peak Reverse Voltage	VRSM	600	V
Average Rectified Forward Current 50Hz Half Sine Wave Resistive Load	IO	1.0	A
		<small>T_a=25°C * 1</small>	
		<small>T_a=25°C * 2</small>	
R.M.S. Forward Current	IF(RMS)	1.57	A
Surge Forward Current 50Hz Half Sine Wave, 1 cycle, Non-repetitive	IFSM	25	A
Operating Junction Temperature Range	T _{jw}	-40 to +150	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Peak Reverse Current	IRM	-	-	10	μA
Peak Forward Voltage	VFM	-	-	1.1	V
Thermal Resistance Junction to Ambient	R _{th(j-a)}	-	-	157	°C /W
		-	-	108	

FORWARD CURRENT VS. VOLTAGE

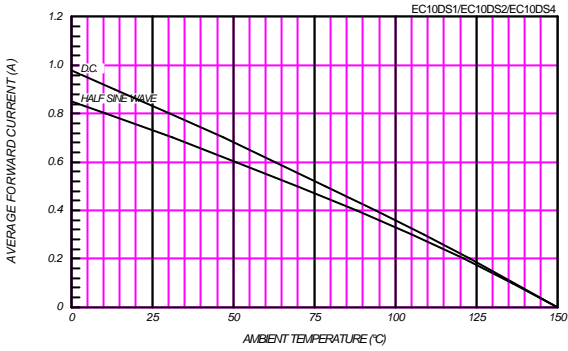


AVERAGE FORWARD POWER DISSIPATION



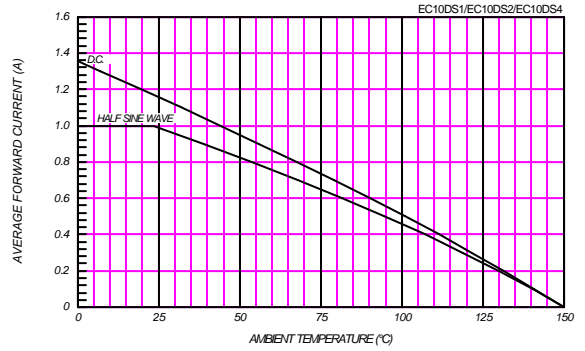
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Glass-Epoxy Substrate Mounted(Soldering Land=2x2mm)



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Alumina Substrate Mounted(Soldering Land=2x2mm)



SURGE CURRENT RATINGS

$f_s=50\text{Hz}$, Half Sine Wave, Non-Repetitive, No Load

